

# PATENT

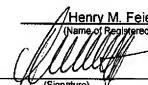
## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Docket No.: MAYERHOFER

In re Application of:	)
ROLAND MAYERHOFER et al.	)
Appl. No.: 10/563,080	) Group Art Unit: 2854
Filed: July 18, 2006	) Confirmation No.: 8118
For: METHOD FOR PRODUCING A PRINTING PLATE FOR INTAGLIO PRINTING AND CORRESPONDING PRINTING PLATE	)

### FOURTH INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

CERTIFICATION OF EFS-WEB TRANSMISSION	
I hereby certify that this paper is being EFS-Web transmitted to the U.S. Patent and Trademark Office, Alexandria VA 22313-1450, on <u>April 30, 2007</u> .	
Date	
<u>Henry M. Feiereisen</u>	
(Name of Registered Representative)	
	<u>4-30-2007</u>
(Signature)	(Date of Signature)

S I R:

In accordance with 37 C.F.R. 1.56, applicant wishes to call the attention of attention of the Examiner to the references listed on enclosed form PTO-1449.

Applicant does not admit that any of the cited documents constitutes prior art against the pending application.

Copies of these references are submitted herewith along with form PTO-1449. The Examiner is requested to initial the attached form PTO-1449 and to return a copy of the initialed document to the undersigned as an indication that the attached references have been considered and made of record.

This Information Disclosure Statement is filed before the mailing of a first Office Action on the merits, so that no fee under 37 C.F.R. §1.97 is due.

In addition, applicant notes with respect to any information that is not in English language as follows:

An English-language Abstract is submitted with respect to Russian Patent No. 264092.

French Patent No. 2775744 describes a friction part having a friction layer consisting of hard ceramic particles (1) dispersed in a small quantity of soft nickel or copper based alloy matrix and has an intercommunicating pore network. A friction part includes a metal substrate coated with a composite friction layer consisting of (by vol.) 20-30% soft nickel or copper based alloy matrix (7) of 250-600 HV hardness, 40-60% dispersed hard ceramic particles (1) of 40-120  $\mu$  size and above 2000 HV hardness, and 20-30% intercommunicating pore network. The matrix consists of a nickel alloy of composition (by wt.) 15% Cr, 4% Fe, 3% B, 4% Si,  $\leq$  1% C, balance Ni and impurities. The substrate consists of a Cu-40Zn-Al brass.

The above-identified application discloses and claims an invention patentable over this prior art. Entry of the references above set forth into the file of the above application is believed to be in order and is respectfully requested.

The Commissioner is hereby authorized to charge any fees which may be required, or credit any overpayment to Deposit Account No. 06-0502.

Respectfully submitted

By: 

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## INFORMATION DISCLOSURE CITATION

<b>Attorney's Docket No.</b>  <b>MAYERHOFER</b>	<b>Applicant</b>  <b>ROLAND MAYERHOFER et al.</b>	<b>Appl. No.</b>  <b>10/563,080</b>
<b>Filing Date</b>  <b>July 18, 2006</b>	<b>Group</b>  <b>2854</b>	<b>Examiner</b>

## U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date, if appropriate
/JZ/	US2001/0043842 A1	11-22-2001	Kaule et al.			

## FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Subclass	Translation
/JZ/	RU 264092	11-10-1970	Russia			
	JP 08120427 A	05-14-1996	Japan			
↓	JP 07308707	11-281995	Japan			
↓	FR 2775744	09-10-1999	France			

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)


<b>Examiner:</b>  /Joshua Zimmerman/	<b>Date considered:</b>  03/11/2008
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\*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.